

## Multilayer board, 26L HDI PCB,FR-4

### Product Description:

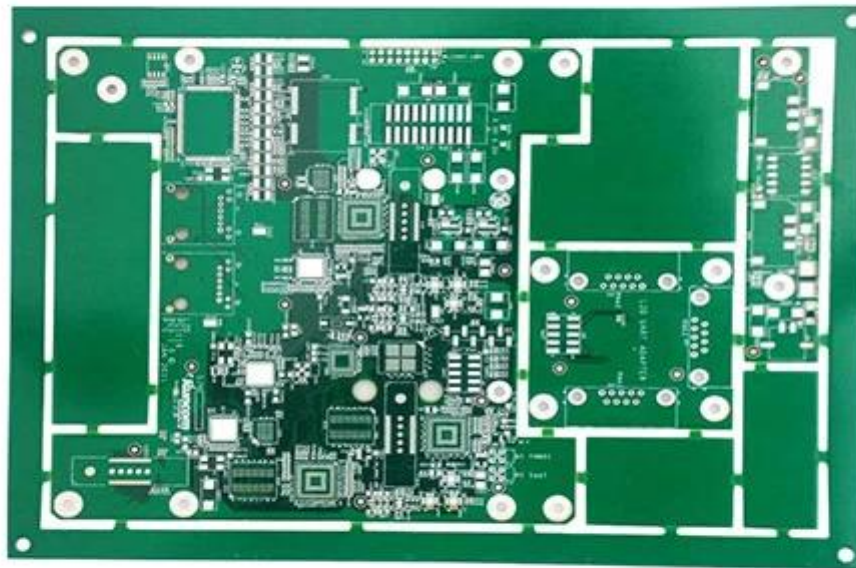
|                   |                                           |                   |                    |
|-------------------|-------------------------------------------|-------------------|--------------------|
| Place of Origin   | Guang dong, China (Mainland)              | Brand Name        | O-Leading          |
| Base Material     | NPG-150N                                  | Copper Thickness  | 1oz                |
| Min. Hole Size    | 0.2mm                                     | Min. Line Width   | 2.35mil            |
| Surface Finishing | immersion gold                            | Min. Line Spacing | 3mil               |
| applicable to     | Industry control                          | character         | Industrial Control |
| certificates      | ISO9001,UL,RoHS,SGS                       | Q/CTN             | 10PCS-100PCS       |
| weight            | 0.01kg -5kg                               | MOQ               | 10pcs              |
| Model Number      | power bank pcb assembly pcba manufacturer | Board Thickness   | 0.1-5mm            |
| color             | green                                     | price             | \$0.1-\$10         |
| design type       | customer requirement                      | size              | 0.01m3-10m3        |

### Packaging & Delivery

|                   |                                                     |
|-------------------|-----------------------------------------------------|
| Packaging Details | 16 years professional OEM client board manufacturer |
| Delivery Detail   | 7-12days                                            |

### Product Description

| item                                      | 2017                                                                                                                                                                    |        | 2018~2020 |        | 2021~2023 |        |
|-------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------|-----------|--------|-----------|--------|
|                                           | Volume                                                                                                                                                                  | Sample | Volume    | Sample | Volume    | Sample |
| Layer count                               | 32                                                                                                                                                                      | 42     | 38        | 44     | 42        | 48     |
| Min Line/space (μm)                       | 50/50                                                                                                                                                                   | 40/45  | 40/45     | 40/40  | 35/40     | 35/35  |
| Min drill hole diameter (mm)              | 0.15                                                                                                                                                                    | 0.10   | 0.15      | 0.10   | 0.15      | 0.10   |
| Aspect ratio of PTH                       | 14:1                                                                                                                                                                    | 16:1   | 16:1      | 18:1   | 18:1      | 20:1   |
| N+C+N                                     | 4+C+4                                                                                                                                                                   | 5+C+5  | 5+C+5     | 6+C+6  | 5+C+5     | 6+C+6  |
| Any layer interconnection                 | 5+2+5                                                                                                                                                                   | 6+2+6  | 5+2+5     | 6+2+6  | 5+2+5     | 6+2+6  |
| Plate filling via                         | YES                                                                                                                                                                     | --     | YES       | --     | YES       | --     |
| Min. core thickness (exclude copper) (μm) | 50                                                                                                                                                                      | 40     | 40        | thirty | 40        | thirty |
| Min. Laser Drill diameter (μm)            | 75                                                                                                                                                                      | 65     | 65        | 50     | 50        | 40     |
| Via on buried hole/stacked via            | YES                                                                                                                                                                     | --     | YES       | --     | YES       | --     |
| Material                                  | FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.                                                                                                                         |        |           |        |           |        |
| Embedded capacitor PCB                    | YES                                                                                                                                                                     | --     | YES       | --     | YES       | --     |
| Surface Process                           | Lead-free HASL, ENIG, OSP, silver with immersion, tin of immersion, Flash of gold, Golden finger coating, Selective solid gold coating, Flaking solder mask, carbon ink |        |           |        |           |        |



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[HDI pcb Printed circuit board](#)